

Certificate TW16/00553

The management system of

Taiwan-Asia Semiconductor Corporation.

NO. 1, Lixing 5th Rd., Hsinchu Science Park, Hsinchu 300094, Taiwan, R.O.C.

has been assessed and certified as meeting the requirements of

ISO 45001:2018

For the following activities

Design and manufacturing of light emitting diode epitaxial wafers, light emitting diode chips, infrared emitting diode chips, photo diode chips, photo transistor chips, zener diode chips, silicon epitaxial wafers, silicon MOSFET chips, schottky diode chips, thermopile detector, optical sensor or receiver IC, LED driver IC, Photo triac, Resistor chips, Light Emitting Diode Package, Assembly, function test and maintenance of wireless & wired communication system application of military. Design and manufacturing of light emitting diode chips, infrared emitting diode chips, photo diode chips.

This certificate is valid from 07 July 2022 until 07 July 2025 and remains valid subject to satisfactory surveillance audits.

Issue 4. Certified since 07 July 2019

Certified activities performed by additional sites are listed on subsequent pages.

Authorised by
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Deputy Director

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Taiwan-Asia Semiconductor Corporation.

ISO 45001:2018

Issue 4
Sites
Taiwan-Asia Semiconductor Corporation. NO. 1, Lixing 5 th Rd., Hsinchu Science Park, Hsinchu 300094, Taiwan, R.O.C. Design and manufacturing of light emitting diode epitaxial wafers, light emitting diode chips, infrared emitting diode chips, photo diode chips, photo transistor chips, zener diode chips, silicon epitaxial wafers, silicon MOSFET chips, schottky diode chips, thermopile detector, optical sensor or receiver IC, LED driver IC, Photo triac, Resistor chips, Light Emitting Diode Package, Assembly, function test and maintenance of wireless & wired communication system application of military. Design and manufacturing of light emitting diode chips, infrared emitting diode chips, photo diode chips.
Taiwan-Asia Semiconductor Corporation. Li-hsin Manufactory NO. 1, Lixing 5 th Rd., Hsinchu Science Park, Hsinchu 300094, Taiwan, R.O.C. Design and manufacturing of light emitting diode epitaxial wafers, light emitting diode chips, infrared emitting diode chips, photo diode chips, photo transistor chips, zener diode chips, silicon epitaxial wafers, silicon MOSFET chips, schottky diode chips, thermopile detector, optical sensor or receiver IC, LED driver IC, Photo triac, Resistor chips, Light Emitting Diode Package, Assembly, function test and maintenance of wireless & wired communication system application of military.
Taiwan-Asia Semiconductor Corporation. Innovation Manufactory NO. 8, Innovation 1 st Rd., Hsinchu Science Park, Hsinchu 300092, Taiwan, R.O.C. Design and manufacturing of light emitting diode chips, infrared emitting diode chips, photo diode chips.



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